

Stella Pang

List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/4468891/publications.pdf>

Version: 2024-02-01

192
papers

5,184
citations

168829

31
h-index

120465

65
g-index

194
all docs

194
docs citations

194
times ranked

5605
citing authors

#	ARTICLE	IF	CITATIONS
1	Engineered barriers regulate osteoblast cell migration in vertical direction. <i>Scientific Reports</i> , 2022, 12, 4459.	1.6	2
2	Compact Terahertz Dielectric Folded Metasurface. <i>Advanced Optical Materials</i> , 2022, 10, .	3.6	8
3	Separation of nasopharyngeal epithelial cells from carcinoma cells on 3D scaffold platforms. <i>Biotechnology and Bioengineering</i> , 2021, 118, 1444-1455.	1.7	4
4	Traversing Behavior of Nasopharyngeal Epithelial and Carcinoma Cells on Two-Layer Scaffold Platforms. , 2021, , .		0
5	Directing osteoblastic cell migration on arrays of nanopillars and nanoholes with different aspect ratios. <i>Lab on A Chip</i> , 2021, 21, 2206-2216.	3.1	10
6	Directing Cell Migration with Patterned Nanostructures. , 2021, , .		1
7	Spreading and Migration of Nasopharyngeal Normal and Cancer Cells on Microgratings. <i>ACS Applied Bio Materials</i> , 2021, 4, 3224-3231.	2.3	3
8	High-Gain Folded Reflectarray Antenna Operating at 1 THz. , 2021, , .		1
9	A three-dimensional spheroid-specific role for Wnt β -catenin and Eph ϵ -ephrin signaling in nasopharyngeal carcinoma cells. <i>Journal of Cell Science</i> , 2021, 134, .	1.2	3
10	Controlled Scaffold Platform Designs on Nasopharyngeal Carcinoma Cell Separation. <i>IEEE Access</i> , 2021, 9, 113813-113822.	2.6	1
11	Microelectrode Array With Integrated Pneumatic Channels for Dynamic Control of Electrode Position in Retinal Implants. <i>IEEE Transactions on Neural Systems and Rehabilitation Engineering</i> , 2021, 29, 2292-2298.	2.7	1
12	Imprint and Si Dry Etching Technologies for THz Antennas at 1 THz. , 2021, , .		0
13	Integration of biochemical and topographic cues for the formation and spatial distribution of invadosomes in nasopharyngeal epithelial cells. <i>Acta Biomaterialia</i> , 2020, 101, 168-182.	4.1	9
14	Capturing instructive cues of tissue microenvironment by silica bioreplication. <i>Acta Biomaterialia</i> , 2020, 102, 114-126.	4.1	9
15	Microfabrication Technology developed for High Gain THz Resonant Antenna with Spherical Fabry-Perot Cavity. , 2020, , .		0
16	Using Biomimetic Scaffold Platform to Detect Growth Factor Induced Changes in Migration Dynamics of Nasopharyngeal Epithelial Cells. <i>IEEE Access</i> , 2020, 8, 187553-187563.	2.6	4
17	Microenvironmental topographic cues influence migration dynamics of nasopharyngeal carcinoma cells from tumour spheroids. <i>RSC Advances</i> , 2020, 10, 28975-28983.	1.7	5
18	Effects of topographical guidance cues on osteoblast cell migration. <i>Scientific Reports</i> , 2020, 10, 20003.	1.6	20

#	ARTICLE	IF	CITATIONS
19	Compact High-Gain Si-Imprinted THz Antenna for Ultrahigh Speed Wireless Communications. IEEE Transactions on Antennas and Propagation, 2020, 68, 5945-5954.	3.1	24
20	3D nanoplasmonic biosensor for detection of filopodia in cells. Lab on A Chip, 2020, 20, 2188-2196.	3.1	10
21	Deconstructing, Replicating, and Engineering Tissue Microenvironment for Stem Cell Differentiation. Tissue Engineering - Part B: Reviews, 2020, 26, 540-554.	2.5	11
22	Traversing behavior of tumor cells in three-dimensional platforms with different topography. PLoS ONE, 2020, 15, e0234482.	1.1	3
23	Migration of immortalized nasopharyngeal epithelia and carcinoma cells through porous membrane in 3D platforms. Bioscience Reports, 2020, 40, .	1.1	6
24	Control of neural probe shank flexibility by fluidic pressure in embedded microchannel using PDMS/PI hybrid substrate. PLoS ONE, 2019, 14, e0220258.	1.1	19
25	Cell migration on microposts with surface coating and confinement. Bioscience Reports, 2019, 39, .	1.1	11
26	Natural killer cell migration control in microchannels by perturbations and topography. Lab on A Chip, 2019, 19, 2466-2475.	3.1	7
27	Cell traction force in a confined microenvironment with double-sided micropost arrays. RSC Advances, 2019, 9, 8575-8584.	1.7	7
28	Dynamic Tracking of Osteoblastic Cell Traction Force during Guided Migration. Cellular and Molecular Bioengineering, 2018, 11, 11-23.	1.0	7
29	Highly sensitive detection of exosomes by 3D plasmonic photonic crystal biosensor. Nanoscale, 2018, 10, 19927-19936.	2.8	39
30	Label-free detection of live cancer cells and DNA hybridization using 3D multilayered plasmonic biosensor. Nanotechnology, 2018, 29, 365503.	1.3	28
31	Neural Probes with Integrated Temperature Sensors for Monitoring Retina and Brain Implantation and Stimulation. IEEE Transactions on Neural Systems and Rehabilitation Engineering, 2017, 25, 1663-1673.	2.7	18
32	A microfabricated low-profile wideband antenna array for terahertz communications. Scientific Reports, 2017, 7, 1268.	1.6	43
33	Substrates with patterned topography reveal metastasis of human cancer cells. Biomedical Materials (Bristol), 2017, 12, 055001.	1.7	28
34	Dynamics of Natural Killer Cells Cytotoxicity in Microwell Arrays with Connecting Channels. Frontiers in Immunology, 2017, 8, 998.	2.2	12
35	A Unidirectional Cell Switching Gate by Engineering Grating Length and Bending Angle. PLoS ONE, 2016, 11, e0147801.	1.1	15
36	High sensitivity plasmonic biosensor based on nanoimprinted quasi 3D nanosquares for cell detection. Nanotechnology, 2016, 27, 295101.	1.3	42

#	ARTICLE	IF	CITATIONS
37	Design, Fabrication, and Measurement of the Low-Loss SOI-Based Dielectric Microstrip Line and its Components. IEEE Transactions on Terahertz Science and Technology, 2016, , 1-10.	2.0	23
38	A 750â€“1000 GHz \$H\$ -Plane Dielectric Horn Based on Silicon Technology. IEEE Transactions on Antennas and Propagation, 2016, 64, 5074-5083.	3.1	18
39	Electrode modifications to lower electrode impedance and improve neural signal recording sensitivity. Journal of Neural Engineering, 2015, 12, 056018.	1.8	68
40	Silicon based THz dielectric waveguides. , 2015, , .		4
41	Effects of three-layered nanodisk size on cell detection sensitivity of plasmon resonance biosensors. Biosensors and Bioelectronics, 2015, 74, 799-807.	5.3	20
42	Large-scale Topographical Screen for Investigation of Physical Neural-Guidance Cues. Scientific Reports, 2015, 5, 8644.	1.6	66
43	Control of cell migration direction by inducing cell shape asymmetry with patterned topography. Journal of Biomedical Materials Research - Part A, 2015, 103, 2383-2393.	2.1	30
44	Influence of engineered surface on cell directionality and motility. Biofabrication, 2014, 6, 015011.	3.7	24
45	Effects of nanoparticle size and cell type on high sensitivity cell detection using a localized surface plasmon resonance biosensor. Biosensors and Bioelectronics, 2014, 55, 141-148.	5.3	39
46	Design of a broadband CPWG to dielectric ridge waveguide transition for terahertz circuits. , 2013, , .		1
47	High resolution patterning on nonplanar substrates with large height variation using electron beam lithography. Journal of Vacuum Science and Technology B:Nanotechnology and Microelectronics, 2012, 30, .	0.6	4
48	Three-dimensional metal patterning over nanostructures by reversal imprint. Journal of Vacuum Science & Technology B, 2008, 26, 632-635.	1.3	12
49	Control of DNA motion in microchannels integrated with dual electrodes. Journal of Vacuum Science & Technology B, 2008, 26, 2578-2582.	1.3	2
50	Patterning of polyfluorene based polymer light emitting diodes by reversal imprint lithography. Journal of Vacuum Science & Technology B, 2008, 26, 2385-2389.	1.3	4
51	The immobilization of DNA molecules to electrodes in confined channels at physiological pH. Nanotechnology, 2008, 19, 465102.	1.3	3
52	Integration of electrodes in Si channels using low temperature polymethylmethacrylate bonding. Journal of Vacuum Science & Technology B, 2007, 25, 368.	1.3	5
53	Characterizing nanoimprint profile shape and polymer flow behavior using visible light angular scatterometry. Journal of Vacuum Science & Technology B, 2007, 25, 2396.	1.3	24
54	Stretching and selective immobilization of DNA in SU-8 micro- and nanochannels. Journal of Vacuum Science & Technology B, 2007, 25, 2352.	1.3	13

#	ARTICLE	IF	CITATIONS
55	Reversal Nanoimprint for Three Dimensional Fluidic Biosystems. , 2007, , .		0
56	Precise DNA placement and stretching in electrode gaps using electric fields in a microfluidic system. Applied Physics Letters, 2007, 90, 083901.	1.5	12
57	Synthetic nanostructures inducing differentiation of human mesenchymal stem cells into neuronal lineage. Experimental Cell Research, 2007, 313, 1820-1829.	1.2	702
58	Stretching and immobilization of DNA for studies of proteinâ€“DNA interactions at the single-molecule level. Nanoscale Research Letters, 2007, 2, 185-201.	3.1	29
59	Real-Time Shape Evolution of Nanoimprinted Polymer Structures during Thermal Annealing. Nano Letters, 2006, 6, 1723-1728.	4.5	74
60	Protein-Assisted Stretching and Immobilization of DNA Molecules in a Microchannel. Nano Letters, 2006, 6, 2499-2504.	4.5	28
61	Three-dimensional nanochannels formed by fast etching of polymer. Journal of Vacuum Science & Technology B, 2006, 24, 1941.	1.3	5
62	Three-dimensional SU-8 structures by reversal UV imprint. Journal of Vacuum Science & Technology B, 2006, 24, 2225.	1.3	41
63	Hybrid mold reversal imprint for three-dimensional and selective patterning. Journal of Vacuum Science & Technology B, 2006, 24, 2968.	1.3	11
64	Multiple level nanochannels fabricated using reversal UV nanoimprint. Journal of Vacuum Science & Technology B, 2006, 24, 2984.	1.3	23
65	Pattern fidelity in nanoimprinted films using critical dimension small angle x-ray scattering. Journal of Micro/ Nanolithography, MEMS, and MOEMS, 2006, 5, 013001.	1.0	11
66	Elastodynamic Characterization of Imprinted Nanolines. Materials Research Society Symposia Proceedings, 2006, 924, 1.	0.1	3
67	Pattern fidelity in nanoimprinted films using CD-SAXS. , 2005, , .		1
68	Nanopattern-induced changes in morphology and motility of smooth muscle cells. Biomaterials, 2005, 26, 5405-5413.	5.7	592
69	Sealed three-dimensional nanochannels. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 2005, 23, 2995.	1.6	13
70	Multiple-stage microfabricated preconcentrator-focuser for micro gas chromatography system. Journal of Microelectromechanical Systems, 2005, 14, 498-507.	1.7	118
71	Effects of nanoimprinted patterns in tissue-culture polystyrene on cell behavior. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 2005, 23, 2984.	1.6	98
72	First-generation hybrid MEMS gas chromatograph. Lab on A Chip, 2005, 5, 1123.	3.1	205

#	ARTICLE	IF	CITATIONS
73	Stability of functional polymers after plasticizer-assisted imprint lithography. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 2004, 22, 3294.	1.6	13
74	Imprinting of polymer at low temperature and pressure. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 2004, 22, 2486.	1.6	33
75	Stacked polymer patterns imprinted using a soft inks pad. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 2004, 22, 1873-1878.	0.9	8
76	Duo-mold imprinting of three-dimensional polymeric structures. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 2004, 22, 3251.	1.6	31
77	Plasticizer-assisted polymer imprint and transfer. , 2004, 5374, 1017.		1
78	Imprinting polymer film on patterned substrates. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 2003, 21, 2742.	1.6	33
79	Polymer inking as a micro- and nanopatterning technique. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 2003, 21, 2749.	1.6	21
80	Microfabricated preconcentrator-focuser for a microscale gas chromatograph. Journal of Microelectromechanical Systems, 2003, 12, 264-272.	1.7	104
81	Thick and thermally isolated Si microheaters for microfabricated preconcentrators. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 2003, 21, 274.	1.6	12
82	Freestanding microheaters in Si with high aspect ratio microstructures. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 2002, 20, 1008.	1.6	13
83	Reversal imprinting by transferring polymer from mold to substrate. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 2002, 20, 2872.	1.6	142
84	Nanoimprinting over topography and multilayer three-dimensional printing. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 2002, 20, 2881.	1.6	133
85	Dry Etching Technology for Optical Devices. , 2002, , 533-562.		0
86	Characteristics of a photonic bandgap single defect microcavity electroluminescent device. IEEE Journal of Quantum Electronics, 2001, 37, 1153-1160.	1.0	65
87	Design and fabrication of submicrometer, single crystal Si accelerometer. Journal of Microelectromechanical Systems, 2001, 10, 518-524.	1.7	35
88	High-Aspect-Ratio Structures for MEMS. MRS Bulletin, 2001, 26, 307-308.	1.7	7
89	Self-aligned process for single electron transistors. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 2001, 19, 1925.	1.6	1
90	Released submicrometer Si microstructures formed by one-step dry etching. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 2001, 19, 433.	1.6	8

#	ARTICLE	IF	CITATIONS
91	Comparison of Cl ₂ and F-based dry etching for high aspect ratio Si microstructures etched with an inductively coupled plasma source. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 2000, 18, 1890.	1.6	60
92	Surface Damage Induced by Dry Etching. , 2000, , 309-360.		7
93	Characterization of bending in single crystal Si beams and resonators. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1999, 17, 1336.	1.6	5
94	Cl ₂ plasma passivation of etch induced damage in GaAs and InGaAs with an inductively coupled plasma source. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1999, 17, 2745.	1.6	8
95	Low-Pressure Etching of Nanostructures and Via Holes Using an Inductively Coupled Plasma System. Journal of the Electrochemical Society, 1999, 146, 775-779.	1.3	22
96	Ultraviolet emission of silicon quantum tips. Applied Physics Letters, 1999, 74, 386-388.	1.5	7
97	High current density Si field emission devices with plasma passivation and HfC coating. IEEE Transactions on Electron Devices, 1999, 46, 792-797.	1.6	18
98	A merged process for thick single-crystal Si resonators and BiCMOS circuitry. Journal of Microelectromechanical Systems, 1999, 8, 221-228.	1.7	13
99	Fabrication of thick Si resonators with a frontside-release etch-diffusion process. Journal of Microelectromechanical Systems, 1998, 7, 201-206.	1.7	15
100	High-aspect-ratio Si vertical micromirror arrays for optical switching. Journal of Microelectromechanical Systems, 1998, 7, 207-213.	1.7	52
101	Dry Etching of Deep Si Trenches for Released Resonators in a Cl ₂ Plasma. Journal of the Electrochemical Society, 1998, 145, 1767-1771.	1.3	9
102	Fabrication of self-aligned silicon field emission devices and effects of surface passivation on emission current. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1998, 16, 765.	1.6	7
103	Direct nano-printing on Al substrate using a SiC mold. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1998, 16, 1145.	1.6	99
104	Dry etching of Si field emitters and high aspect ratio resonators using an inductively coupled plasma source. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1998, 16, 2849.	1.6	23
105	Electrical and optical characteristics of etch induced damage in InGaAs. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1998, 16, 3359.	1.6	11
106	Electronic properties of GaAs surfaces etched in an electron cyclotron resonance source and chemically passivated using P2S5. Applied Physics Letters, 1998, 73, 114-116.	1.5	8
107	Novel approach to surface imaging. , 1998, , .		0
108	<title>High-aspect-ratio single-crystal Si microelectromechanical systems</title>. , 1998, 3511, 242.		1

#	ARTICLE	IF	CITATIONS
109	Effects of graded superlattice on endpoint detection for low damage heterojunction bipolar transistor etching. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1997, 15, 681.	1.6	11
110	Etching and boron diffusion of high aspect ratio Si trenches for released resonators. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1997, 15, 267.	1.6	13
111	Etching of high aspect ratio microcavity structures in InP. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1997, 15, 665.	1.6	6
112	Time dependence of etch-induced damage generated by an electron cyclotron resonance source. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1997, 15, 2643.	1.6	13
113	Field emission from gated Si emitter tips with precise gate tip spacing, gate diameter, tip sharpness, and tip protrusion. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1997, 15, 2777.	1.6	8
114	<title>Optical interferometric characterization of membrane curvature in boron-doped Si microstructures</title>. , 1997, 3223, 142.		0
115	High reflectivity micromirrors fabricated by coating high aspect ratio Si sidewalls. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1997, 15, 2661.	1.6	5
116	Modeling and algorithm development for automated optical endpointing of an HBT emitter etch. Journal of Electronic Materials, 1997, 26, 1401-1408.	1.0	3
117	Gallium arsenide surface chemistry and surface damage in a chlorine high density plasma etch process. Journal of Electronic Materials, 1997, 26, 1320-1325.	1.0	19
118	Released Si microstructures fabricated by deep etching and shallow diffusion. Journal of Microelectromechanical Systems, 1996, 5, 18-23.	1.7	33
119	Controlling sidewall smoothness for micromachined Si mirrors and lenses. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1996, 14, 4080.	1.6	63
120	Relating electric field distribution of an electron cyclotron resonance cavity to dry etching characteristics. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 1996, 14, 2020-2025.	0.9	10
121	Characterization of GaAs Surfaces Subjected to A Cl ₂ /Ar High Density Plasma Etching Process. Materials Research Society Symposia Proceedings, 1996, 448, 33.	0.1	0
122	Control of etch profile for fabrication of Si microsensors. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 1996, 14, 1189-1193.	0.9	9
123	Simulation and dry etching of field emitter tips in Si. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 1996, 14, 1832-1838.	0.9	7
124	In situ fiber optic thermometry of wafer surface etched with an electron cyclotron resonance source. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1996, 14, 1807.	1.6	8
125	Dry etching of horizontal distributed Bragg reflector mirrors for waveguide lasers. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1996, 14, 4119.	1.6	20
126	Effects of etch-induced damage on the electrical characteristics of in-plane gated quantum wire transistors. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1996, 14, 3663.	1.6	4

#	ARTICLE	IF	CITATIONS
127	Minimized response time of optical emission and mass spectrometric signals for optimized endpoint detection. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1996, 14, 2531.	1.6	19
128	Sharpening Si field emitter tips by dry etching and low temperature plasma oxidation. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1996, 14, 3697.	1.6	7
129	Fabrication of Si field emitters by dry etching and mask erosion. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1996, 14, 612.	1.6	22
130	Response Time For Optical Emission And Mass Spectrometric Signals During Etching Of Heterostructures. Materials Research Society Symposia Proceedings, 1995, 406, 27.	0.1	0
131	In-Situ Fiberoptic Thermometry Measurements Of Wafer Temperature During Plasma Etching Using An Electron Cyclotron Resonance Source. Materials Research Society Symposia Proceedings, 1995, 406, 75.	0.1	0
132	Investigation of reactive-ion-etch-induced damage of InP/InGaAs multiple quantum wells by photoluminescence. Journal of Applied Physics, 1995, 78, 1528-1532.	1.1	13
133	Effects of electron cyclotron resonance etching on the ambient (100) GaAs surface. Applied Physics Letters, 1995, 66, 3054-3055.	1.5	13
134	High-aspect-ratio Si etching for microsensor fabrication. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 1995, 13, 834-838.	0.9	24
135	Monitoring InP and GaAs etched in Cl ₂ /Ar using optical emission spectroscopy and mass spectrometry. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 1995, 13, 894-899.	0.9	40
136	The influence of ion energy, ion flux, and etch temperature on the electrical and material quality of GaAs etched with an electron cyclotron resonance source. Journal of Applied Physics, 1995, 78, 2712-2715.	1.1	6
137	Si nanostructures fabricated by anodic oxidation with an atomic force microscope and etching with an electron cyclotron resonance source. Applied Physics Letters, 1995, 66, 1729-1731.	1.5	75
138	<title>Dry micromachining of high-aspect-ratio Si for microsensors</title>. , 1995, , .		1
139	Atomic force microscopy study of III-V materials etched using an electron cyclotron resonance source. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1995, 13, 2350.	1.6	7
140	Plasma passivation of etch-induced surface damage on GaAs. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1995, 13, 2376.	1.6	11
141	Fabrication of dry etched mirrors for In _{0.20} Ga _{0.80} As/GaAs waveguides using an electron cyclotron resonance source. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1995, 13, 2709.	1.6	2
142	In situ monitoring of GaAs etched with a Cl ₂ /Ar discharge in an electron cyclotron resonance source. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1995, 13, 253.	1.6	6
143	High Aspect Ratio Deep Via Holes in InP Etched Using Cl ₂ /Ar Plasma. Journal of the Electrochemical Society, 1995, 142, 3945-3949.	1.3	25
144	Electrical Characterization and Surface Analysis of Dry Etch-Induced Damage on Si after Etching in an ECR Source. Journal of the Electrochemical Society, 1995, 142, 206-211.	1.3	31

#	ARTICLE	IF	CITATIONS
145	Mass Spectrometry, Optical Emission Spectroscopy, and Atomic Force Microscopy Studies of Si Etch Characteristics in a Cl ₂ Plasma Generated by an Electron Cyclotron Resonance Source. Japanese Journal of Applied Physics, 1994, 33, 7112-7116.	0.8	18
146	Characterization of etch-induced damage for Si etched in Cl ₂ plasma generated by an electron cyclotron resonance source. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 1994, 12, 1346-1350.	0.9	6
147	Dependence of contact resistivity and Schottky diode characteristics on dry etching induced damage of GaInAs. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1994, 12, 2941.	1.6	13
148	High aspect ratio polyimide etching using an oxygen plasma generated by electron cyclotron resonance source. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1994, 12, 422.	1.6	30
149	Surface Damage on GaAs Etched Using a Multipolar Electron Cyclotron Resonance Source. Journal of the Electrochemical Society, 1994, 141, 255-258.	1.3	10
150	Evaluation of surface damage on GaAs etched with an electron cyclotron resonance source. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1994, 12, 3382.	1.6	16
151	Dependence of etch characteristics on charge particles as measured by Langmuir probe in a multipolar electron cyclotron resonance source. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 1994, 12, 69-74.	0.9	10
152	<title>Photoreflectance study of the chemically modified (100) GaAs surface</title>. , 1994, 2141, 96.		4
153	Photolithographic micromolding of ceramics using plasma etched polyimide patterns. Applied Physics Letters, 1993, 63, 3379-3381.	1.5	22
154	Photoluminescence and electro-optic properties of small (25-35 nm diameter) quantum boxes. Applied Physics Letters, 1993, 62, 2766-2768.	1.5	30
155	Etching of Si with Cl ₂ using an electron cyclotron resonance source. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 1993, 11, 1206-1210.	0.9	15
156	Effects of reactive ion etching on optical and electro-optical properties of GaInAs/InP based strip-loaded waveguides. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1993, 11, 1214.	1.6	12
157	Low Temperature Etching of Silylated Resist in an Oxygen Plasma Generated by an Electron Cyclotron Resonance Source. Journal of the Electrochemical Society, 1993, 140, 3620-3623.	1.3	1
158	<title>Planarization film by plasma-enhanced chemical vapor deposition and low-temperature oxide as conformal insulator</title>. , 1993, 1805, 18.		0
159	Photoreflectance Characterization of Etch-Induced Damage in Dry Etched GaAs. Materials Research Society Symposia Proceedings, 1993, 324, 153.	0.1	4
160	Relating Photoresist Etch Characteristics to Langmuir Probe Measurements in an Electron Cyclotron Resonance Source. Materials Research Society Symposia Proceedings, 1993, 324, 305.	0.1	0
161	In-Situ Monitoring by Mass Spectrometry for GaAs Etched with An Electron Cyclotron Resonance Source. Materials Research Society Symposia Proceedings, 1993, 324, 329.	0.1	1
162	Evaluation of Dry Etching Induced Damage of GaInAs Using Transmission Lines and Schottky Diodes. Materials Research Society Symposia Proceedings, 1993, 324, 421.	0.1	0

#	ARTICLE	IF	CITATIONS
163	Selective Etching of Bilayer Photoresist Using a Multipolar Electron Cyclotron Resonance Source. Journal of the Electrochemical Society, 1992, 139, 3599-3602.	1.3	2
164	Relative fluorine concentrations in radio frequency/electron cyclotron resonance hybrid glow discharges. Applied Physics Letters, 1992, 60, 818-820.	1.5	3
165	Comparison between etching in Cl ₂ and BCl ₃ for compound semiconductors using a multipolar electron cyclotron resonance source. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1992, 10, 2703.	1.6	11
166	Etching of photoresist using oxygen plasma generated by a multipolar electron cyclotron resonance source. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1992, 10, 1118.	1.6	14
167	Oxidation of silicon in an oxygen plasma generated by a multipolar electron cyclotron resonance source. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1992, 10, 2211.	1.6	24
168	<title>Enhanced etching of InP by cycling with sputter etching and reactive ion etching</title>. , 1991, , .		0
169	Low Temperature Silicon Oxidation with Electron Cyclotron Resonance Oxygen Plasma. Materials Research Society Symposia Proceedings, 1991, 236, 319.	0.1	0
170	Low Temperature Silicon Oxidation With Electron Cyclotron Resonance Oxygen Plasma. Materials Research Society Symposia Proceedings, 1991, 235, 781.	0.1	0
171	A Comparison Between Dry Etching with an Electron Cyclotron Resonance Source and Reactive Ion Etching for GaAs and InP. Materials Research Society Symposia Proceedings, 1991, 240, 273.	0.1	0
172	Etching of GaAs and InP using a hybrid microwave and radio-frequency system. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1991, 9, 3530.	1.6	7
173	High-speed resonant-tunneling diodes made from the In _{0.53} Ga _{0.47} As/AlAs material system. , 1990, , .		17
174	Plasma-deposited organosilicon thin films as dry resists for deep ultraviolet lithography. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1990, 8, 1493.	1.6	30
175	Plasma-deposited amorphous carbon films as planarization layers. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1990, 8, 1980.	1.6	17
176	Aluminum oxides as imaging materials for 193-nm excimer laser lithography. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1989, 7, 1624.	1.6	10
177	Dry etching induced damage on vertical sidewalls of GaAs channels. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1988, 6, 1916.	1.6	53
178	Emerging technology for in situ processing: Patterning alternatives. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1988, 6, 895.	1.6	14
179	Submicrometer Structures Fabricated by Masked Ion Beam Lithography and Dry Etching. Journal of the Electrochemical Society, 1988, 135, 1526-1529.	1.3	0
180	Pattern transfer by dry etching through stencil masks. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1988, 6, 249.	1.6	16

#	ARTICLE	IF	CITATIONS
181	Masked ion beam lithography for submicrometer-gate-length transistors. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1987, 5, 215.	1.6	14
182	Cermet as an inorganic resist for ion lithography. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1987, 5, 379.	1.6	6
183	Hot-jet etching of Pb, GaAs, and Si. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1987, 5, 363.	1.6	20
184	Nanometer-scale columns in GaAs fabricated by angled chlorine ion-beam-assisted etching. Applied Physics Letters, 1987, 51, 1726-1728.	1.5	7
185	Surface Damage on GaAs Induced by Reactive Ion Etching and Sputter Etching. Journal of the Electrochemical Society, 1986, 133, 784-787.	1.3	124
186	Hot Jet Etching through Stencil Masks. Materials Research Society Symposia Proceedings, 1986, 76, 143.	0.1	0
187	Sub-100-nm-wide, deep trenches defined by reactive ion etching. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1986, 4, 341.	1.6	3
188	Effects of ion species and adsorbed gas on dry etching induced damage in GaAs. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1985, 3, 398.	1.6	52
189	Damage induced in Si by ion milling or reactive ion etching. Journal of Applied Physics, 1983, 54, 3272-3277.	1.1	114
190	Effects of dry etching on GaAs. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1983, 1, 1334.	1.6	100
191	Interface state generation in the Si-SiO ₂ system by photoinjecting electrons from an Al field plate. Applied Physics Letters, 1982, 40, 709-711.	1.5	34
192	Microfabricated preconcentrator for quantitative analysis of low concentration volatile organic compounds. , 0, , .		4